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## M1MA151AT1, M1MA152AT1

**Preferred Device** 

# Single Silicon Switching Diodes

These Silicon Epitaxial Planar Diodes are designed for use in ultra high speed switching applications. These devices are housed in the SC-59 package which is designed for low power surface mount applications.

#### **Features**

- Fast  $t_{rr}$ , < 3.0 ns
- Low C<sub>D</sub>, < 2.0 pF
- Pb-Free Packages are Available

## **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit	
Reverse Voltage	M1MA151AT1 M1MA152AT1	V <sub>R</sub>	40 80	Vdc
Peak Reverse Voltage	M1MA151AT1 M1MA152AT1	V <sub>RM</sub>	40 80	Vdc
Forward Current		I <sub>F</sub>	100	mAdc
Peak Forward Current		I <sub>FM</sub>	225	mAdc
Peak Forward Surge Cur	rent	I <sub>FSM</sub> (Note 1)	500	mAdc

#### THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	P <sub>D</sub>	200	mW
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

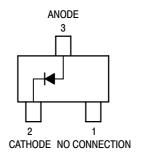
1. t = 1 SEC



## ON Semiconductor®

http://onsemi.com

## SC-59 PACKAGE SINGLE SILICON SWITCHING DIODES 40/80 V-100 mA SURFACE MOUNT





SC-59 CASE 318D

## **MARKING DIAGRAM**



Mx = Device Code

x = A for 151

B for 152

M = Date Code\*= Pb-Free Package

= = Fb-itee Fackage

(Note: Microdot may be in either location)
\*Date Code orientation may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

## M1MA151AT1, M1MA152AT1

## **ELECTRICAL CHARACTERISTICS** $(T_A = 25^{\circ}C)$

Characteristic		Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	M1MA151AT1 M1MA152AT1	I <sub>R</sub>	V <sub>R</sub> = 35 V V <sub>R</sub> = 75 V	-	0.1	μAdc
Forward Voltage		V <sub>F</sub>	I <sub>F</sub> = 100 mA	-	1.2	Vdc
Reverse Breakdown Voltage	M1MA151AT1 M1MA152AT1	V <sub>R</sub>	I <sub>R</sub> = 100 μA	40 80	-	Vdc
Diode Capacitance		C <sub>D</sub>	V <sub>R</sub> = 0, f = 1.0 MHz	-	2.0	pF
Reverse Recovery Time (Figure 1)		t <sub>rr</sub> (Note 2)	$I_F = 10 \text{ mA}, V_R = 6.0 \text{ V},$ $R_L = 100 \Omega, I_{rr} = 0.1 I_R$	-	3.0	ns

<sup>2.</sup> t<sub>rr</sub> Test Circuit

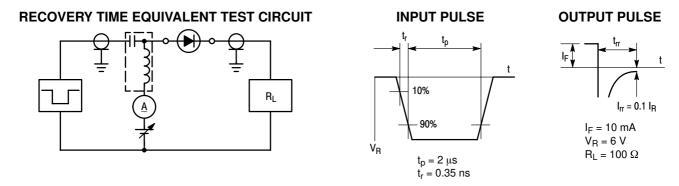


Figure 1. Reverse Recovery Time Equivalent Test Circuit

## **ORDERING INFORMATION**

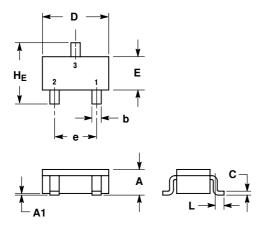
Device	Package	Shipping <sup>†</sup>
M1MA151AT1	SC-59	
M1MA151AT1G	SC-59 (Pb-Free)	3000 /Tape & Reel
M1MA152AT1	SC-59	3000/Tape & Neel
M1MA152AT1G	SC-59 (Pb-Free)	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## M1MA151AT1, M1MA152AT1

#### PACKAGE DIMENSIONS

SC-59 CASE 318D-04 ISSUE G

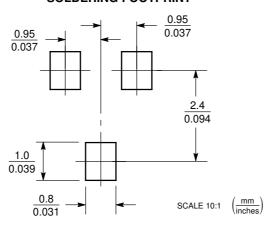


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS				INCHES	
	MILLIMETERS					
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.15	1.30	0.039	0.045	0.051
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.35	0.43	0.50	0.014	0.017	0.020
С	0.09	0.14	0.18	0.003	0.005	0.007
D	2.70	2.90	3.10	0.106	0.114	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
е	1.70	1.90	2.10	0.067	0.075	0.083
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.80	3.00	0.099	0.110	0.118

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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